INDUSTRIAL SESSION
Monday, 8:00 pm • Thurgood Marshall Ballroom

8:00 pm  Wolfspeed, A Cree Company (Golden Sponsor)
Wolfspeed Materials Update
Speaker: Chris Dimino

8:08 pm  II-VI Advanced Materials
Status of Large Diameter Crystal Growth at II-VI
Speaker: Andy Souzis

8:16 pm  Dow Corning
Dow Silicon Carbide Update
Speaker: Edward Sanchez

8:24 pm  PowerAmerica (Major Sponsor)
Enabling High Volume Wide Bandgap Semiconductor Manufacturing: the PowerAmerica Value Proposition
Speaker: Jim LeMunyon

8:32 pm  Infineon Technologies (Major Sponsor)
Join us for a Journey into the Future—
SiC Accelerate @ Infineon
Speaker: Peter Friedrichs

8:40 pm  AIXTRON SE
Meeting Advanced SiC MOSFET Production Specifications with 150 mm SiC Batch Planetary Reactor Technology
Speaker: Frank Wischmeyer

8:48 pm  Sumitomo Electric Industries, Ltd.
High Quality SiC Epi Wafer Epitaxy and SiC V-groove Trench MOSFET
Speaker: Keiji Wada

8:56 pm  NuFlare Technology, Inc.
NuFlare’s Single Wafer SiC Epitaxial Reactor EPIREVO S6
Speaker: Itaru Fujiki

9:04 pm  KLA-Tencor Corporation
Candela Defect Inspection Update for SiC and GaN Power Market
Speaker: Anoop Somanchi

9:12 pm  Laserlec Corporation
SICA for SiC High Volume Manufacturing Inspection Solutions
Speaker: Eru Yamamura

9:20 pm  Nissin Ion Equipment Co., Ltd.
High Temperature Ion Implantation System—IMPHEAT
Speaker: Chihiro Takada

9:28 pm  Revasum
Economical Back-side Thinning and Polishing of SiC
Speaker: Sarah Okada

9:36 pm  KITEC microelectronic technologie GmbH
Non-Contact Resistance Measurement Today
Speaker: Klaus Topp

9:44 pm  Rigaku Corporation
X-ray Metrology Tool Line up for Silicon Carbide
Speaker: Kenichi Itoi

9:52 pm  3D-Micromac AG
Enabling Laser Systems for Manufacturing of SiC Devices
Speaker: Hans-Ulrich Zuehlke